

# Specification of Thermoelectric Module

**TEFC1-05535**

### Description

The 55 couples, 7 mm × 15 mm size ingte module which is made of selected high performance ingot to achieve superior cooling performance and greater delta T up to 70 °C, designed for superior cooling and heating up to 100 °C /200 °C applications. If higher operation or processing temperature is required, please specify, we can design and manufacture the custom made module according to your special requirements.

### Features

- No moving parts, no noise, and solid-state
- Compact structure, small in size, light in weight
- Environmental friendly
- RoHS compliant
- Precise temperature control
- Exceptionally reliable in quality, high performance

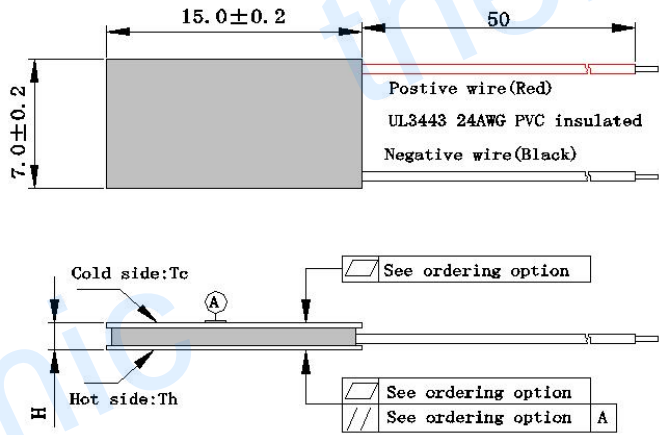
### Application

- Food and beverage service refrigerator
- Portable cooler box for cars
- Liquid cooling
- Temperature stabilizer
- CPU cooler and scientific instrument
- Photonic and medical systems

### Performance Specification Sheet

Th (°C)	27	50	Hot side temperature at environment: dry air, N <sub>2</sub>
DT <sub>max</sub> (°C)	70	79	Temperature Difference between cold and hot side of the module when cooling capacity is zero at cold side
U <sub>max</sub> (Voltage)	6.82	7.37	Voltage applied to the module at DT <sub>max</sub>
I <sub>max</sub> (amps)	3.46	3.46	DC current through the modules at DT <sub>max</sub>
Q <sub>Cmax</sub> (Watts)	15.2	16.4	Cooling capacity at cold side of the module under DT=0 °C
AC resistance (ohms)	1.50	1.62	The module resistance is tested under AC
Tolerance (%)	10%		For thermal and electricity parameters

### Geometric Characteristics Dimensions in millimeters



### Manufacturing Options

- |   |   |
|---|---|
| <p><b>A. Solder:</b></p> <ol style="list-style-type: none"> <li>1. T100: BiSn (T<sub>mel</sub>=138°C)</li> <li>2. T200: CuSn (T<sub>mel</sub>=227°C)</li> </ol> <p><b>B. Sealant:</b></p> <ol style="list-style-type: none"> <li>1. NS: No sealing (Standard)</li> <li>2. SS: Silicone sealant</li> <li>3. EPS: Epoxy sealant</li> <li>4. Customer specify sealing</li> </ol> | <p><b>C. Ceramics:</b></p> <ol style="list-style-type: none"> <li>1. Alumina (Al<sub>2</sub>O<sub>3</sub>, white 96%)</li> <li>2. Aluminum Nitride (AlN)</li> </ol> <p><b>D. Ceramics Surface Options:</b></p> <ol style="list-style-type: none"> <li>1. Blank ceramics (not metalized)</li> <li>2. Metalized (Cu plating)</li> </ol> |
|---|---|

### Ordering Option

Suffix	Thickness H (mm)	Flatness/ Parallelism (mm)	Lead wire length(mm) Standard/Optional length
TF	0: 1.6±0.10	0: 0.03/0.03	50±3/Specify
TF	1: 1.6±0.05	1: 0.02/0.02	50±3/Specify
TF	2: 1.6±0.03	2: 0.01/0.01	50±3/Specify

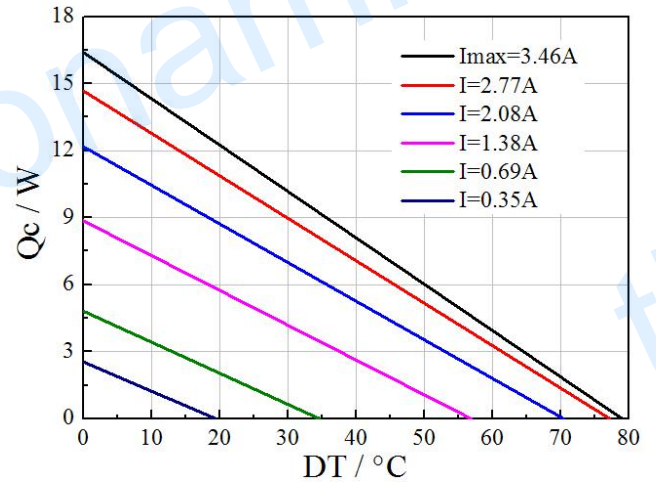
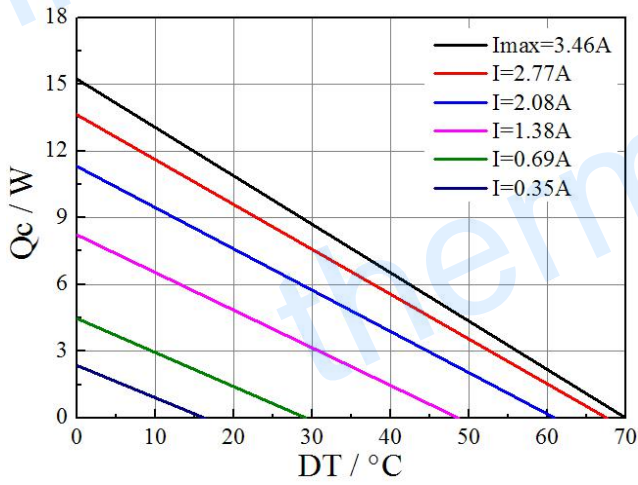
Eg. TF01: Thickness 1.6± 0.10 (mm) and Flatness 0.02 / 0.02(mm)

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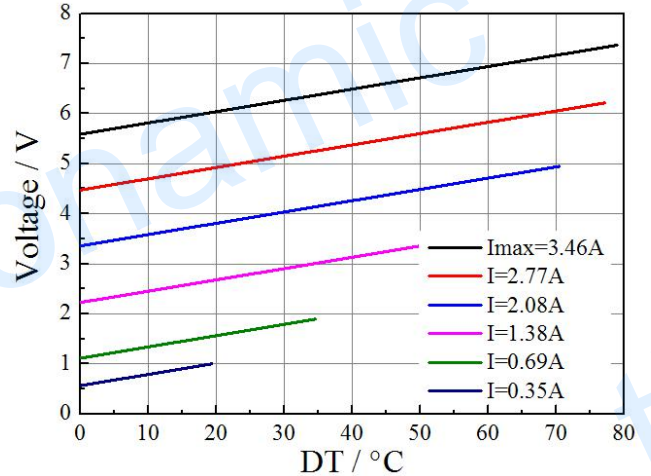
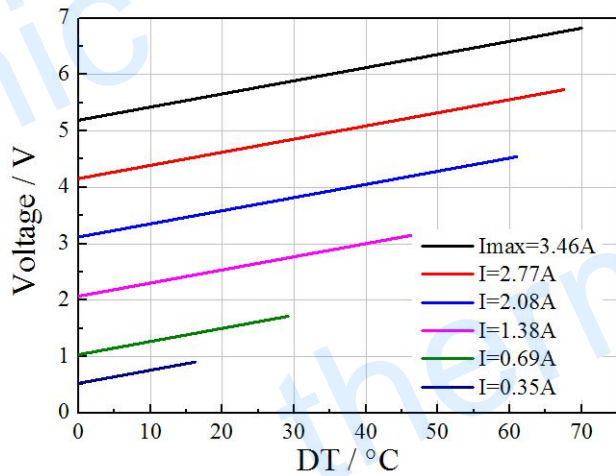
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## Performance Curves at $T_h=27^\circ\text{C}$

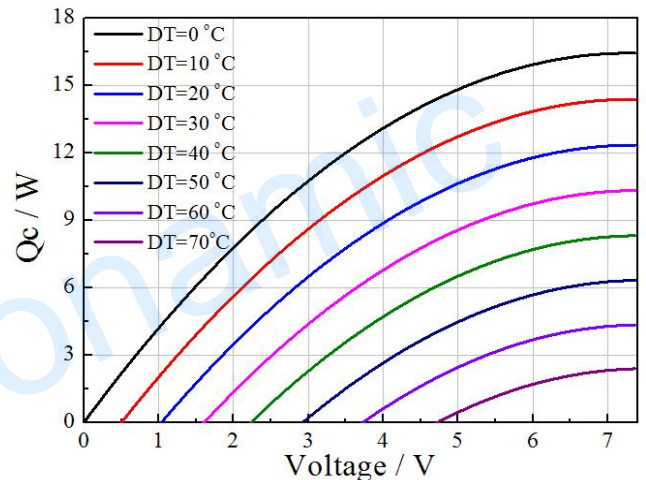
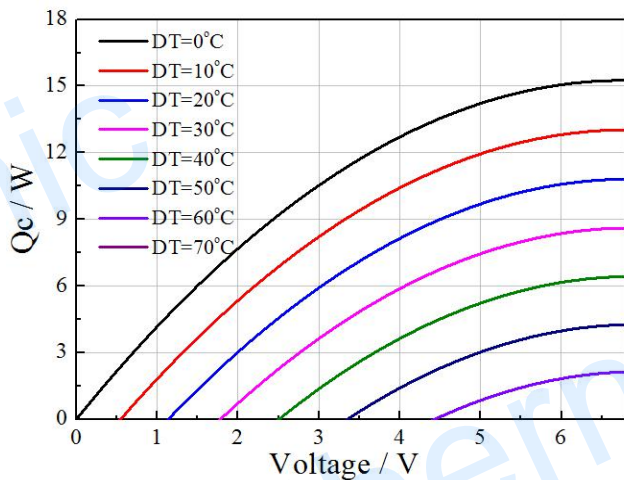
## Performance Curves at $T_h=50^\circ\text{C}$



Standard Performance Graph  $Q_c = f(DT)$



Standard Performance Graph  $V = f(DT)$

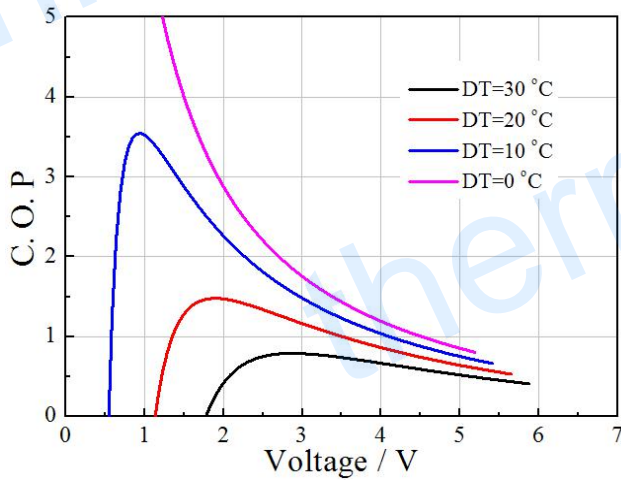


Standard Performance Graph  $Q_c = f(V)$

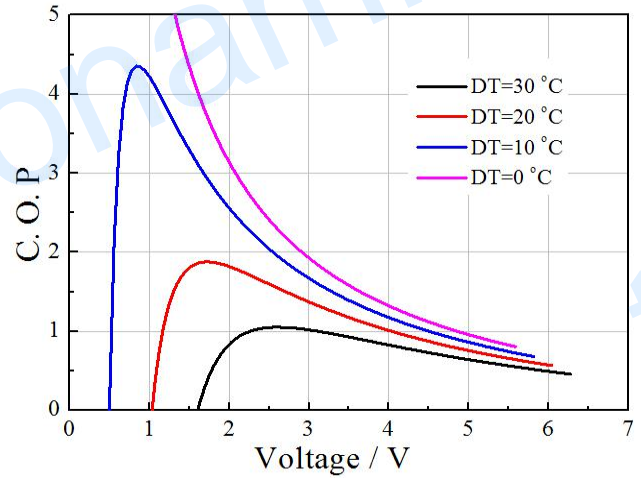
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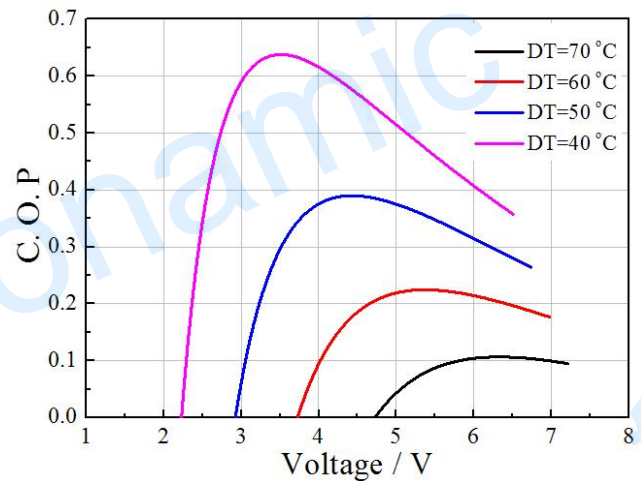
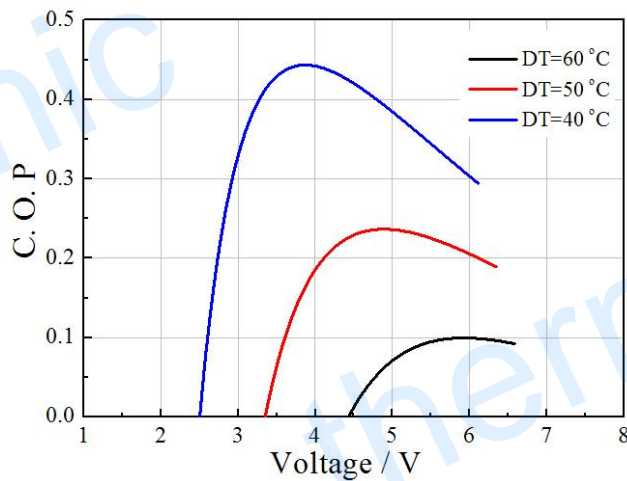
### Performance Curves at Th=27 °C



### Performance Curves at Th=50 °C



Standard Performance Graph COP = f(V) of DT ranged from 0 to 30 °C



Standard Performance Graph COP = f(V) of DT ranged from 40 to 60/70 °C

**Remark:** The coefficient of performance (COP) is the cooling power  $Q_c$ /Input power ( $V \times I$ ).

### Operation Cautions

- Attach the cold side of module to the object to be cooled
- Attach the hot side of module to a heat radiator for heat dissipating
- Operation below  $I_{max}$  or  $V_{max}$
- Work under DC

**Note:** All specifications subject to change without notice.